

QUADRUPLE OPERATIONAL AMPLIFIER

FEATURES

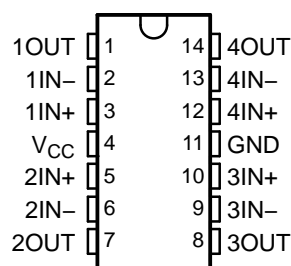
- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication Site
- **Extended Temperature Performance of -55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree**

(1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- **ESD Protection <500 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model C = 200 pF, R = 0); 1500 V Using Charged Device Model**
- **ESD Human Body Model >2 kV Machine Model >200 V and Charge Device Model = 2 kV For K-Suffix Devices.**
- **Low Supply-Current Drain Independent of Supply Voltage . . . 0.8 mA Typ**
- **Low Input Bias and Offset Parameters:**
 - Input Offset Voltage . . . 3 mV Typ
 - Input Offset Current . . . 2 nA Typ
 - Input Bias Current . . . 20 nA Typ

- **Common-Mode Input Voltage Range Includes Ground, Allowing Direct Sensing Near Ground**
- **Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage:**
 - Non-V devices . . . 26 V
 - V-Suffix devices . . . 32 V
- **V-Suffix devices . . . 32 V D Open-Loop Differential Voltage Amplification . . . 100 V/mV Typ**
- **Internal Frequency Compensation**

**D OR PW PACKAGE
(TOP VIEW)**



DESCRIPTION

This device consists of four independent high-gain frequency-compensated operational amplifiers that are designed specifically to operate from a single supply over a wide range of voltages. Operation from split supplies is possible when the difference between the two supplies is 3 V to 26 V (3 V to 32 V for V-suffixed devices) and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. The low supply-current drain is independent of the magnitude of the supply voltage.

Applications include transducer amplifiers, dc amplification blocks, and all the conventional operational-amplifier circuits that now can be more easily implemented in single-supply voltage systems. For example, the LM2902 can be operated directly from the standard 5-V supply that is used in digital systems and easily provides the required interface electronics without requiring additional ±15-V supplies.



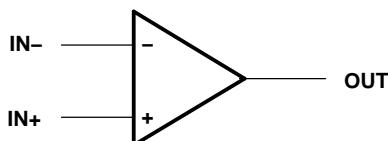
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

ORDERING INFORMATION

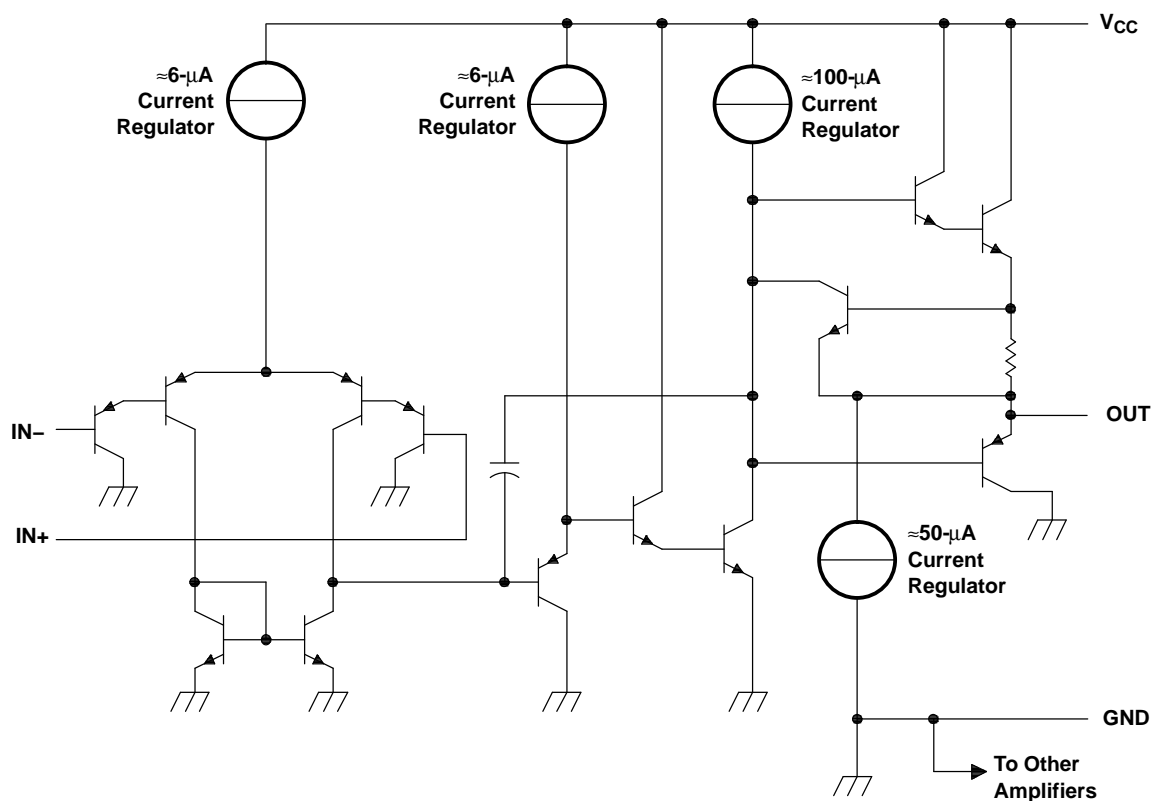
T_A	V_{IO} max AT 25°C	MAX V_{CC}	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	7 mV	26 V	SOIC (D)	Reel of 2500	LM2902QDREP ⁽²⁾	2902EP
			TSSOP(PW)	Reel of 2500	LM2902QPWREP ⁽²⁾	2902EP
	7 mV	32 V	SOIC (D)	Reel of 2500	LM2902KVQDREP ⁽²⁾	2902KVE
			TSSOP(PW)	Reel of 2500	LM2902KVQPWREP ⁽²⁾	2902KVE
	3 mV	32 V	SOIC (D)	Reel of 2500	LM2902KAVQDREP ⁽²⁾	LM2902E
			TSSOP(PW)	Reel of 2500	LM2902KAVQPWREP	LM2902E
–55°C to 125°C	7 mV	26 V	SOIC (D)	Reel of 2500	LM2902MDREP ⁽²⁾	2902ME
			TSSOP(PW)	Reel of 2000	LM2902MPWREP ⁽²⁾	2902ME
	7 mV	32 V	SOIC (D)	Reel of 2500	LM2902KVMDREP ⁽²⁾	2902KME
			TSSOP(PW)	Reel of 2000	LM2902KVMPWREP ⁽²⁾	2902KME
	3 mV	32 V	SOIC (D)	Reel of 2500	LM2902KAVMDREP ⁽²⁾	2902KAE
			TSSOP(PW)	Reel of 2000	LM2902KAVMPWREP ⁽²⁾	2902KAE

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

(2) Product Preview

SYMBOL (EACH AMPLIFIER)

SCHEMATIC (EACH AMPLIFIER)



COMPONENT COUNT (TOTAL DEVICE)	
Epi-FET	1
Transistors	95
Diodes	4
Resistors	11
Capacitors	4

ABSOLUTE MAXIMUM RATINGSover operating free-air temperature range (unless otherwise noted)⁽¹⁾

		LM2902-EP	LM2902KV-EP	UNIT
V_{CC}	Supply voltage ⁽²⁾	26	32	V
V_{ID}	Differential input voltage ⁽³⁾	± 26	± 32	V
V_I	Input voltage (either input)	–0.3 to 26	–0.3 to 32	V
Duration of output short circuit (one amplifier) to ground at (or below) $T_A = 25^\circ\text{C}$, $V_{CC} \leq 15\text{ V}$ ⁽⁴⁾		Unlimited	Unlimited	
θ_{JA}	Package thermal impedance ⁽⁵⁾⁽⁶⁾	D package (0 LFPM)	101	$^\circ\text{C/W}$
		PW package	113	
T_J	Operating virtual junction temperature	142	142	$^\circ\text{C}$
T_{stg}	Storage temperature range ⁽⁷⁾	–65 to 150	–65 to 150	$^\circ\text{C}$

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values, except differential voltages and V_{CC} specified for the measurement of I_{OS} , are with respect to the network GND.

(3) Differential voltages are at IN+ with respect to IN–.

(4) Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.

(5) Maximum power dissipation is a function of $T_J(\text{max})$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 142°C can affect reliability.

(6) The package thermal impedance is calculated in accordance with JESD 51-7.

(7) Long term high-temperature storage and/or extended use at maximum recommended operating conditions may result in reduction of overall device life. See http://www.ti.com/ep_quality for additional information on enhanced plastic packaging.

ELECTRICAL CHARACTERISTICS

at specified free-air temperature, $V_{CC} = 5\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS ⁽¹⁾	T_A ⁽²⁾	LM2902-EP			UNIT
			MIN	TYP ⁽³⁾	MAX	
V_{IO} Input offset voltage	$V_{CC} = 5\text{ V to } 26\text{ V}$, $V_{IC} = V_{ICR\min}$, $V_O = 1.4\text{ V}$	25°C		3	7	mV
		Full range			10	
I_{IO} Input offset current	$V_O = 1.4\text{ V}$	25°C		2	50	nA
		Full range			300	
I_{IB} Input bias current	$V_O = 1.4\text{ V}$	25°C		–20	–250	nA
		Full range			–500	
V_{ICR} Common-mode input voltage range	$V_{CC} = 5\text{ V to } 26\text{ V}$	25°C		0 to $V_{CC} - 1.5$		V
		Full range		0 to $V_{CC} - 2$		
V_{OH} High-level output voltage	$R_L = 10\text{ k}\Omega$	25°C		$V_{CC} - 1.5$		V
	$V_{CC} = 26\text{ V}$, $R_L = 2\text{ k}\Omega$	Full range		22		
	$V_{CC} = 26\text{ V}$, $R_L \geq 10\text{ k}\Omega$	25°C		23	24	
V_{OL} Low-level output voltage	$R_L \leq 10\text{ k}\Omega$	Full range		5	20	mV
A_{VD} Large-signal differential voltage amplification	$V_{CC} = 15\text{ V}$, $V_O = 1\text{ V to } 11\text{ V}$, $R_L \geq 2\text{ k}\Omega$	25°C		100		V/mV
		Full range		15		
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICR\min}$	25°C		50	80	dB
k_{SVR} Supply-voltage rejection ratio ($\Delta V_{CC}/\Delta V_{IO}$)		25°C		50	100	dB
V_{O1}/V_{O2} Crosstalk attenuation	$f = 1\text{ kHz to } 20\text{ kHz}$	25°C		120		dB
I_O Output current	$V_{CC} = 15\text{ V}$, $V_{ID} = 1\text{ V}$, $V_O = 0$	25°C		–20	–30	mA
		Full range		–10		
	$V_{CC} = 15\text{ V}$, $V_{ID} = -1\text{ V}$, $V_O = 15\text{ V}$	25°C		10	20	mA
		Full range		5		
	$V_{ID} = -1\text{ V}$, $V_O = 200\text{ mV}$	25°C		30		μA
I_{OS} Short-circuit output current	V_{CC} at 5 V, $V_O = 0$, GND at –5 V	25°C		± 40	± 60	mA
I_{CC} Supply current (four amplifiers)	$V_O = 2.5\text{ V}$, No load	Full range		0.7	1.2	mA
	$V_{CC} = 26\text{ V}$, $V_O = 0.5 V_{CC}$, No load	Full range		1.4	3	

(1) All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified.

(2) Full range is –55°C to 125°C.

(3) All typical values are at $T_A = 25^\circ\text{C}$.

ELECTRICAL CHARACTERISTICSat specified free-air temperature, $V_{CC} = 5\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS ⁽¹⁾		T_A ⁽²⁾	LM2902KV-EP			UNIT
				MIN	TYP ⁽³⁾	MAX	
V_{IO} Input offset voltage	$V_{CC} = 5\text{ V to } 32\text{ V},$ $V_{IC} = V_{ICR\min}, V_O = 1.4\text{ V}$	Non-A devices	25°C		3	7	mV
			Full range			10	
		A-suffix devices	25°C		1	3	
			Full range			4.5	
$\Delta V_{IO}/\Delta T$ Temperature drift	$R_S = 0\ \Omega$		Full range		7		$\mu\text{V}/^\circ\text{C}$
I_{IO} Input offset current	$V_O = 1.4\text{ V}$		25°C		2	50	nA
			Full range			150	
$\Delta V_{IO}/\Delta T$ Temperature drift			Full range		10		$\text{pA}/^\circ\text{C}$
I_{IB} Input bias current	$V_O = 1.4\text{ V}$		25°C		–20	–250	nA
			Full range			–500	
V_{ICR} Common-mode input voltage range	$V_{CC} = 5\text{ V to } 32\text{ V}$		25°C		0 to $V_{CC} - 1.5$		V
			Full range		0 to $V_{CC} - 2$		
V_{OH} High-level output voltage	$R_L = 10\text{ k}\Omega$		25°C		$V_{CC} - 1.5$		V
	$V_{CC} = 32\text{ V}, R_L = 2\text{ k}\Omega$		Full range		26		
	$V_{CC} = 32\text{ V}, R_L \geq 10\text{ k}\Omega$		Full range		27		
V_{OL} Low-level output voltage	$R_L = 10\text{ k}\Omega$		Full range		5	20	mV
A_{VD} Large-signal differential voltage amplification	$V_{CC} = 15\text{ V}, V_O = 1\text{ V to } 11\text{ V},$ $R_L \geq 2\text{ k}\Omega$		25°C		25	100	V/mV
			Full range		15		
Amplifier-to-amplifier coupling ⁽⁴⁾	$f = 1\text{ kHz to } 20\text{ kHz},$ input referred		25°C		120		dB
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICR\min}$		25°C		60	80	dB
k_{SVR} Supply-voltage rejection ratio ($\Delta V_{CC}/\Delta V_{IO}$)			25°C		60	100	dB
V_{O1}/V_{O2} Crosstalk attenuation	$f = 1\text{ kHz to } 20\text{ kHz}$		25°C		120		dB
I_O Output current	$V_{CC} = 15\text{ V}, V_{ID} = 1\text{ V}, V_O = 0$		25°C		–20	–30	mA
			Full range		–10		
	$V_{CC} = 15\text{ V}, V_{ID} = -1\text{ V}, V_O = 15\text{ V}$		25°C		10	20	mA
			Full range		5		
	$V_{ID} = -1\text{ V}, V_O = 200\text{ mV}$		25°C		12	40	μA
I_{OS} Short-circuit output current	V_{CC} at 5 V, GND at –5 V	$V_O = 0,$	25°C		± 40	± 60	mA
I_{CC} Supply current (four amplifiers)	$V_O = 2.5\text{ V},$	No load	Full range		0.7	1.2	mA
	$V_{CC} = 32\text{ V},$ $V_O = 0.5 V_{CC},$	No load	Full range		1.4	3	

(1) All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified.

(2) Full range is -55°C to 125°C .(3) All typical values are at $T_A = 25^\circ\text{C}$.

(4) Due to proximity of external components, ensure that coupling is not originating via stray capacitance between these external parts. Typically, this can be detected, as this type of coupling increases at higher frequencies.

OPERATING CONDITIONS

$V_{CC} = \pm 15\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
SR Slew rate at unity gain	$R_L = 1\text{ M}\Omega$, $C_L = 30\text{ pF}$, $V_I = \pm 10\text{ V}$ (see Figure 1)	0.5	$\text{V}/\mu\text{s}$
B_1 Unity-gain bandwidth	$R_L = 1\text{ M}\Omega$, $C_L = 20\text{ pF}$ (see Figure 1)	1.2	MHz
V_n Equivalent input noise voltage	$R_S = 100\ \Omega$, $V_I = 0\text{ V}$, $f = 1\text{ kHz}$ (see Figure 2)	35	$\text{nV}/\sqrt{\text{Hz}}$

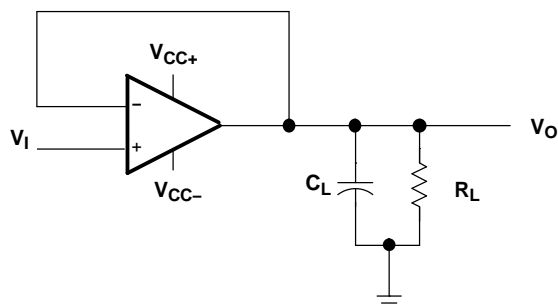


Figure 1. Unity-Gain Amplifier

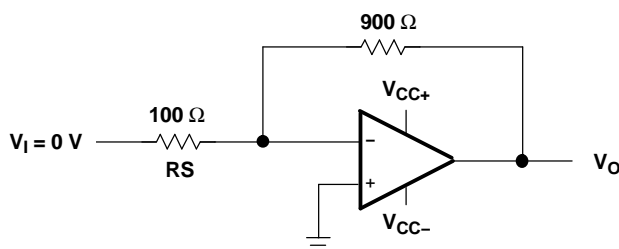


Figure 2. Noise-Test Circuit

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LM2902KAVMPWREP	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	2902KAE
LM2902KAVMPWREP.A	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	2902KAE
LM2902KAVQPWREP	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902E
LM2902KAVQPWREP.A	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902E
V62/06622-01XE	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902E
V62/06622-04XE	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	2902KAE

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF LM2902-EP :

- Catalog : [LM2902](#)
- Automotive : [LM2902-Q1](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM2902KAVMPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902KAVQPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM2902KAVMPWREP	TSSOP	PW	14	2000	353.0	353.0	32.0
LM2902KAVQPWREP	TSSOP	PW	14	2000	353.0	353.0	32.0

PW0014A

PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220202/B 12/2023

NOTES:

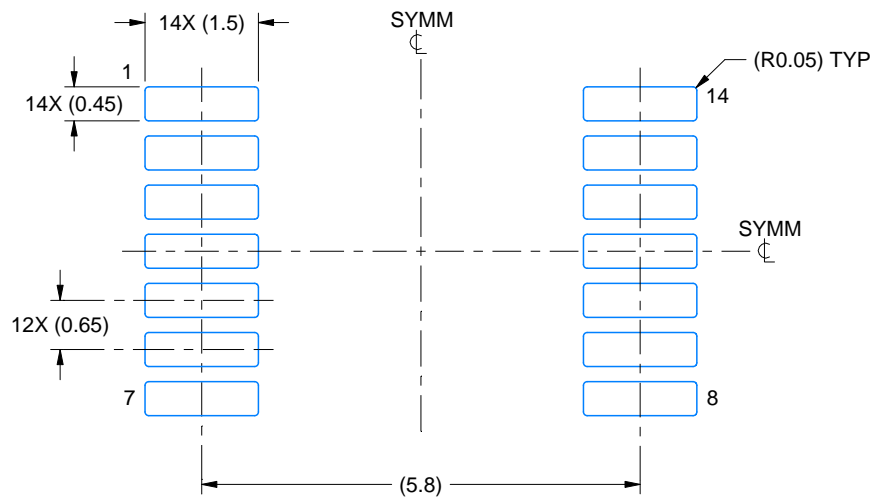
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2025, Texas Instruments Incorporated